EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2943	257/784	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 14:41
L2	2526	257/780	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 14:47
L5	5558	257/778	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 15:15
L6	371	257/731	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 16:04
L7	2323	257/707	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 16:09
L8	3053	257/706	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 16:27
L9	2843	257/700	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 17:20

L10	1536	257/685	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 17:30
L11	2429	257/668	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 17:50
L12	2842	257/698	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 18:02
L13	1770	361/767	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 18:20
L14	4835	438/106	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 18:37
L15	2404	438/107	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 18:37
S1	2	"6608389" or "6521978"	USPAT	OR	OFF	2006/11/06 22:27
S2	890	257/796	USPAT	OR	OFF	2005/06/17 18:12
S3	1	"6246115".PN.	USPAT	OR	OFF	2004/06/15 17:27
S4	1	"6316822".PN.	USPAT	OR	OFF	2004/06/15 17:28
S5	1	"6429513".PN.	USPAT	OR	OFF	2004/06/15 17:28
S6	1	"6472743".PN.	USPAT	OR	OFF	2004/06/15 17:28

S7	1	"6507107".PN.	USPAT	OR	OFF	2004/06/15 17:28
S8	1	"6507107".PN.	USPAT	OR	OFF	2004/06/15 17:29
S9	1	"6528882".PN.	USPAT	OR	OFF	2004/06/15 17:29
S10	0	"2002/0079567".PN.	USPAT	OR	OFF	2004/06/15 17:29
S11	0	"2002/0185734".PN.	USPAT	OR	OFF	2004/06/15 17:29
S12	0	"2003/0047798".PN.	USPAT	OR	OFF	2004/06/15 17:29
S13	0	"2003/0057545".PN.	USPAT	OR	OFF	2004/06/15 17:29
S14	2015	257/706	USPAT	OR	OFF	2004/11/23 22:22
S15	16	"6475830".pn. "6392896".pn. "6335221".pn. "6297551".pn. "6239482".pn. "6208525".pn. "6157080".pn. "6075289".pn. "6069793".pn. "5999437".pn. "5986886".pn. "5872700".pn. "5872051".pn. "5807791".pn. "5784264".pn. "5642262".pn.	USPAT	OR	OFF	2004/09/30 15:49
S16	2	"20020074669".pn. or "20020017721".pn.	US-PGPUB; USPAT	OR	OFF	2004/09/30 15:50
S17	1	"20020195704"	US-PGPUB; USPAT	OR	OFF	2004/11/23 21:17
S18	2542	257/706	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 12:51
S19	1252	257/796	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/23 22:35
S20	2752	257/724	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 12:59
S21	3971	257/723	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 13:22

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S22	509	257/731	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 13:42
S23	1262	257/685	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 13:57
S24	4429	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 13:57
S25	12	bare near (die or chip or IC) and packaged near (chip or die or IC) and Heatsink	USPAT	OR	OFF	2005/03/02 22:47
S26	15	bare near (die or chip or IC) same packaged near (chip or die or IC) same Heat	USPAT	OR	ON	2005/03/03 11:41
S27	13	bare near (die or chip or IC) with (uncapsulat$3 or mold$3) and packaged near (chip or die or IC) and Heat	USPAT	OR	ON	2005/03/03 12:09
S28	15	bare near (die or chip or IC or semiconductor) with (uncapsulat$3 or mold$3) and packaged near (chip or die or IC or semiconductor) and Heat	USPAT	OR	ON	2005/03/03 12:11
S29	38	bare near (die or chip or IC or semiconductor) same (uncapsulat$3 or mold$3) and packaged near (chip or die or IC or semiconductor) and Heat	USPAT	OR	ON	2005/03/03 12:15
S30	183	bare near (die or chip or IC or semiconductor) and (uncapsulat$3 or mold$3) and packaged near (chip or die or IC or semiconductor) and Heat	USPAT	OR	ON	2005/03/03 17:39
S31	6	non-packaged near (die or chip or IC or semiconductor) and (uncapsulat$3 or mold$3) and packaged near (chip or die or IC or semiconductor) and Heat	USPAT	OR	ON	2005/03/03 17:25

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S32	7	(non or none) near packaged near (die or chip or IC or semiconductor) and (uncapsulat$3 or mold$3) and packaged near (chip or die or IC or semiconductor) and Heat	USPAT	OR	ON	2005/03/03 17:26
S33	163	bare near (die or chip or IC or semiconductor) and (uncapsulat$3 or mold$3) and packaged near (chip or die or IC or semiconductor) and (cover or lid)	USPAT	OR	ON	2005/03/03 18:16
S34	11	257/685 and bare near (die or chip or IC or semiconductor) same (encapsulat$3 or mold$3) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 18:20
S35	304	bare near (die or chip or IC or semiconductor) same (encapsulat$3 or mold$3) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 18:48
S36	2086	bare near (die or chip or IC or semiconductor) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 21:01
S37	18	bare near (die or chip or IC or semiconductor) same (encapsulat$3 or mold$3) and (cover or lid or heat or cap)	JPO	OR	ON	2005/03/03 18:48
S38	1782	S36 not S35	USPAT	OR	ON	2005/03/03 18:51
S39	19	(non-packaged or none-packaged or (non or none) near packaged) near (die or chip or IC or semiconductor) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 21:03
S40	32904	(die or chip or IC or semiconductor) with (encapsulat$3 or mold$3 or cover$3 near resin) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 21:04
S41	462	257/685 and (die or chip or IC or semiconductor) with (encapsulat$3 or mold$3 or cover$3 near resin) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 21:31
S42	1	"5754410".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:09
S43	1	"5757074".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:09
S44	1	"6064219".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:09

S45	1	"6246252".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:09
S46	1	"6246252".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:10
S47	1	"6278286".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:10
S48	1	"4410927".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:15
S49	1	"4826297".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:15
S50	1	"5040994".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:17
S51	1	"5134546".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:17
S52	1	"5434745".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:17
S53	1	"5981043".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:17
S54	1	"6380616".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:17
S55	1	"6445254".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:18
S56	1	"6545368".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:18
S57	1	"20020027763".PN.	US-PGPUB	OR	OFF	2005/03/03 21:18
S58	1	"20030071348".PN.	US-PGPUB	OR	OFF	2005/03/03 21:18
S59	4230	S40 and module	USPAT	OR	ON	2005/03/03 21:32
S60	1033	S59 and heat near sink	USPAT	OR	ON	2005/03/03 22:51
S61	1	"4699593".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:41
S62	1	"5371654".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:41
S63	1	"5384955".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:42
S64	1	"5468681".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:42
S65	1	"5477082".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:42
S66	1	"5557502".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:42
S67	1	"5570274".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:42

S68	1	"5594275".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S69	1	"5598033".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S70	1	"5639989".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S71	1	"5691041".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S72	1	"5796170".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S73	1	"5834848".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S74	1	"5838551".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:44
S75	1	"5854534".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:44
S76	1	"5953214".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:45
S77	1	"5977640".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:45
S78	1	"5978229".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:45
S79	1	"6344688".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:45
S80	1	"4151547".PN.	USPAT; USOCR	OR	OFF	2005/03/03 22:09
S81	37	heat near sink with metal near cap	USPAT	OR	ON	2005/03/03 22:51
S82	970	257/796	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/17 18:20
S83	1260	257/685	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/17 18:20
S84	2736	257/706	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 13:21

S85	2736	257/706	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 13:34
S86	0	S84 not S85	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 12:53
S87	12	"5424573".pn. or "5616957".pn. or "5977626".pn. or "6414385". pn. or "6437984".pn. or "6608769".pn. or "6703698".pn. or "6734552".pn. or "6849940". pn. or "20010008776".pn. or "20020175421".pn. or "20020195270".pn.	US-PGPUB; USPAT	OR	OFF	2006/01/19 13:23
S88	1043	257/796	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 13:49
S89	3443	257/787	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 15:45
S90	2617	257/784	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 16:04
S91	1368	257/685	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 16:20
S92	2291	257/780	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 17:05

S93	4933	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 17:34
S94	340	257/731	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 17:45
S95	3895	257/723	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 18:24
S96	2289	257/724	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 18:24
S97	6	("20020195704" | "5754410" | "5757074" | "6064219" | "6246252" | "6278286").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/20 16:30
S98	61818	"6630727".pn. without with (adhesive or glue)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/20 16:30
S99	0	"6630727".pn. and without with (adhesive or glue)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/20 16:35
S100	11	("20020027763" | "20030071348" | "4410927" | "4826297" | "5040994" | "5134546" | "5434745" | "5981043" | "6380616" | "6445254" | "6545368").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/20 16:34
S101	1715	wir$3 with (chip or die or IC or semiconductor) and without with (adhesive or glue)	USPAT	OR	OFF	2006/01/20 16:40
S102	1018	S101 and (mold$3 or encapsulat$3)	USPAT	OR	OFF	2006/01/20 16:40
S103	9	("5365656").URPN.	USPAT	OR	OFF	2006/01/20 16:37
S104	87	wir$3 with (chip or die or IC or semiconductor) with without with (adhesive or glue)	USPAT	OR	OFF	2006/01/20 16:52

S10 5	48	S104 and (mold$3 or encapsulat$3)	USPAT	OR	OFF	2006/01/20 16:41
S10 6	154	wir$3 with (chip or die or IC or semiconductor) and (chip or die or IC or semiconductor) with attach$3 with without with (adhesive or glue)	USPAT	OR	ON	2006/01/20 17:05
S10 7	12	wir$3 with (chip or die or IC or semiconductor) and (chip or die or IC or semiconductor) with attach$3 with directly with without with (adhesive or glue)	USPAT	OR	ON	2006/01/20 17:07
S10 8	1	wir$3 with (chip or die or IC or semiconductor) and (chip or die or IC or semiconductor) with attach$3 with directly near substrate with without with (adhesive or glue)	USPAT	OR	ON	2006/01/20 17:07
S10 9	1	wir$3 with (chip or die or IC or semiconductor) and (chip or die or IC or semiconductor) with attach$3 with directly near substrate with without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:07
S11 0	1	(chip or die or IC or semiconductor) with attach$3 with directly near substrate with without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:08
S11 1	3	(chip or die or IC or semiconductor) with attach$3 with directly near (substrate or board$3 or carrier or hous$3) with without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:10
S11 2	12	(chip or die or IC or semiconductor) with directly near (substrate or board$3 or carrier or hous$3) with without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:11
S11 3	3	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly near (substrate or board$3 or carrier or hous$3) with without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:12
S11 4	96	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly near (substrate or board$3 or carrier or hous$3) and without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:19

S11 5	21	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly near (substrate or board$3 or carrier or hous$3) and without near (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:22
S11 6	98	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly with (substrate or board$3 or carrier or hous$3) and without near (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:27
S11 7	77	S116 not S114	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:23
S11 8	112	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly with (substrate or board$3 or carrier or hous$3) and without near (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:30
S11 9	14	S118 not S116	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:28
S12 0	0	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly with (substrate or board$3 or carrier or hous$3) and "not" with us$3 near (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:41
S12 1	0	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly with (substrate or board$3 or carrier or hous$3) and "don't" with us$3 near (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:31
S12 2	0	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly with (substrate or board$3 or carrier or hous$3) and "don't" with us$3 with (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:32
S12 3	0	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly with (substrate or board$3 or carrier or hous$3) and "not" with us$3 with (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:32

S12 4	470	wir$3 near bond$3 with (chip or die or IC or semiconductor) with directly with (substrate or board$3 or carrier or hous$3)	USPAT	OR	ON	2006/01/20 17:32
S12 5	46	wir$3 near bond$3 with (chip or die or IC or semiconductor) with directly near (substrate or board$3 or carrier or hous$3)	USPAT	OR	ON	2006/01/20 17:33
S12 6	3	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly with (substrate or board$3 or carrier or hous$3) and lack$3 near (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:43
S12 7	0	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly with (substrate or board$3 or carrier or hous$3) and absent$3 near (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:43
S12 8	4	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly with (substrate or board$3 or carrier or hous$3) and absenc$3 near (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:44
S12 9	145	wir$3 near bond$3 and (chip or die or IC or semiconductor) with (absenc$3 or lack$3 or without) near (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:53
S13 0	1087	wir$3 near bond$3 and (chip or die or IC or semiconductor) with (absenc$3 or lack$3 or without) with (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:54
S13 1	80	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly with (absenc$3 or lack$3 or without) with (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:02
S13 2	136	wir$3 near bond$3 and (chip or die or IC or semiconductor) with directly same (absenc$3 or lack$3 or without) with (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:09

S13 3	56	S132 not S131	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:03
S13 4	1528	wir$3 near bond$3 and (chip or die or IC or semiconductor) same (absenc$3 or lack$3 or without) with (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:18
S13 5	1392	S134 not S132	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:19
S13 6	273	wir$3 near bond$3 and (chip or die or IC or semiconductor) same (absenc$3 or lack$3 or without) near (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:22
S13 7	251	S136 not S132	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:23
S13 8	909	(chip or die or IC or semiconductor) same (absenc$3 or lack$3 or without) near (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:22
S13 9	476	wir$3 and (chip or die or IC or semiconductor) same (absenc$3 or lack$3 or without) near (adhesive or glue or underfill or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:34
S14 0	454	S139 not S132	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:34
S14 1	387	wir$3 and (chip or die or IC or semiconductor) same (absenc$3 or lack$3 or without) near (adhesive or glue or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:50
S14 2	367	S141 not S132	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:34
S14 3	354	wir$3 and (chip or die or IC or semiconductor) near bare with directly and (adhesive or glue or attach$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 19:09
S14 4	1	"6630727".pn. and coverlayer with heat	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 19:42

S14 5	7	"5471366".pn. or "6069023".pn. or "6140144".pn. or "6316840". pn. or "6574860".pn. or "6929976".pn. or "20020025608". pn.	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 19:42
S14 6	4	257/E25.023	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/06 22:28
S14 7	4323	257/723	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/06 22:35
S14 8	2509	257/724	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 11:46
S14 9	1137	257/796	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 13:10
S15 0	3800	257/787	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/07 14:15